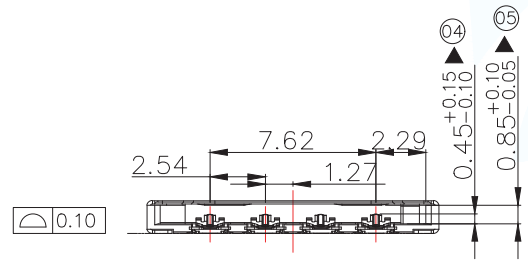
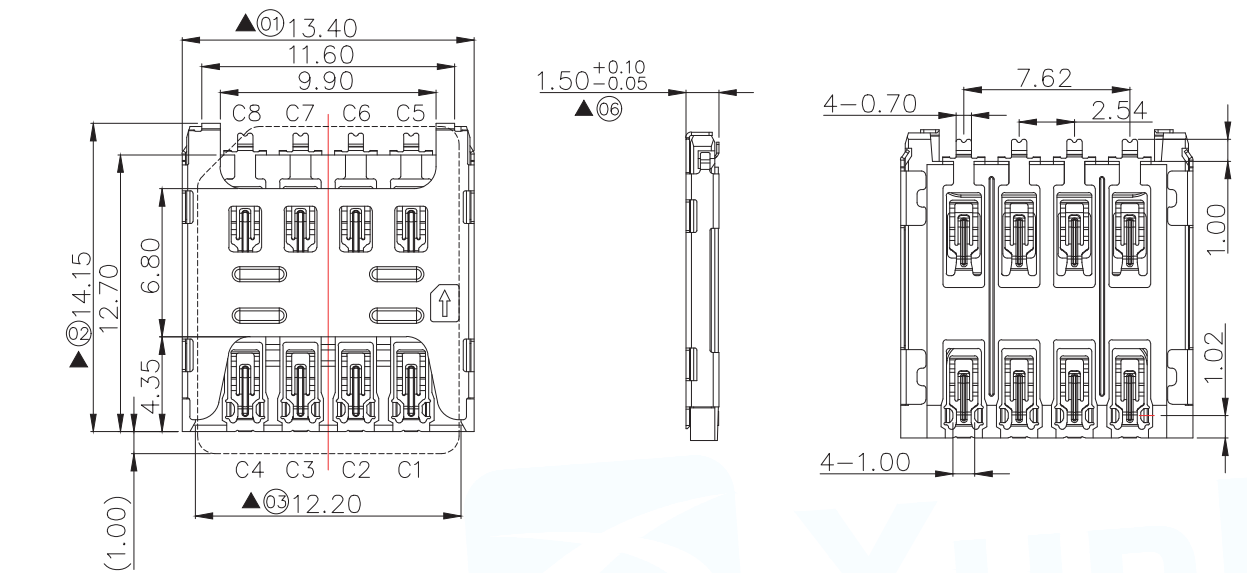
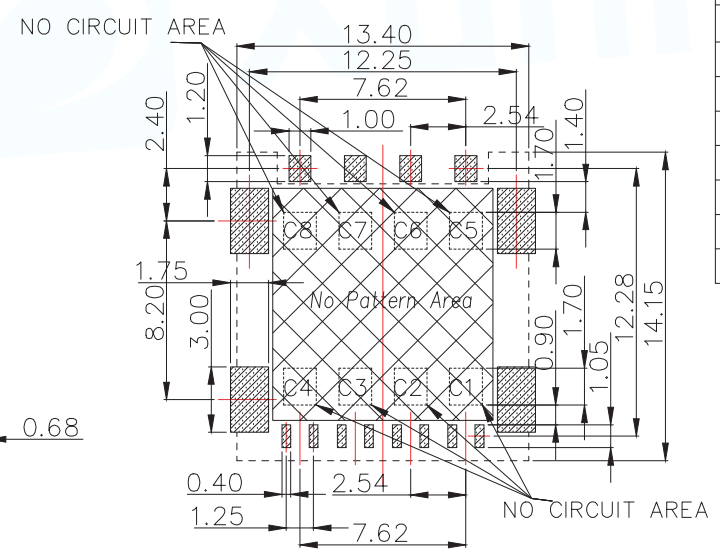
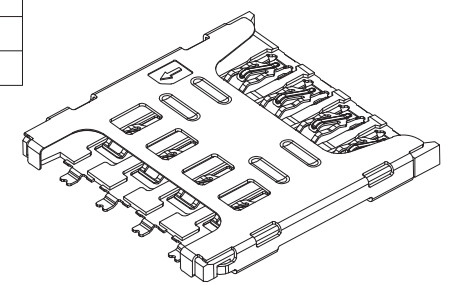
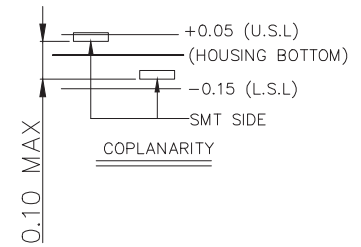


NOTES:

- ELECTRICAL CHARACTERISTICS
  - CONTACT RESISTANCE: 100 MILLIOHMS MAX
  - INSULATION RESISTANCE: 1,000 MEGOHMS MIN.
  - VOLTAGE RATING: 50V.
  - CURRENT RATING: 1.0A.
- MECHANICAL CHARACTERISTICS
  - OPERATION TEMPERATURE RANGE:  $-20^{\circ}\text{C} \sim +85^{\circ}\text{C}$
  - DURABILITY: 5000 CYCLES
- MATERIAL:
  - HOUSING: THERMOPLASTIC, UL 94-V0
  - CONTACT: COPPER ALLOY,  $T=0.10$
  - SHELL: STAINLESS STEEL,  $T=0.15$
- FINISHED:
  - CONTACT: NI PLATED UNDER, AU PLATED ON CONTACT AREA, G/F PLATED ON SOLDER TAIL
  - SHELL: NI PLATED UNDER, G/F PLATED ON SOLDER TAIL

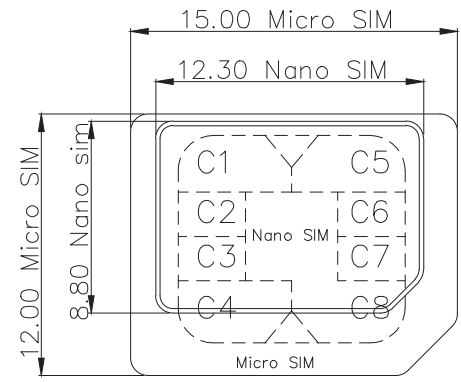


MICRO SIM CARD	
Pin No.	NAME
C1	VCC OF SIM
C2	RST OF SIM
C3	CLK OF SIM
C5	GND OF SIM
C6	VPP OF SIM
C7	I/O OF SIM
C4/C8	N/A

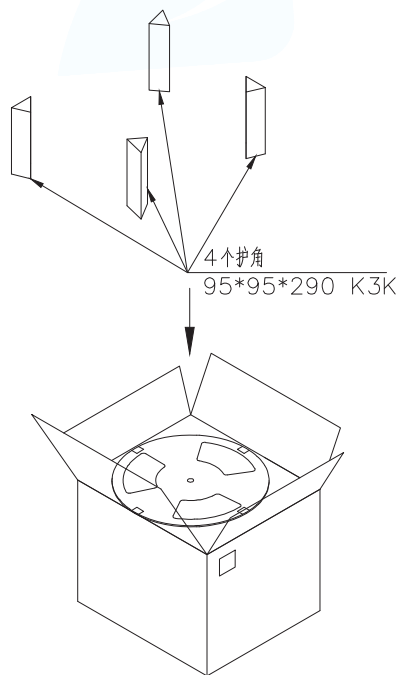
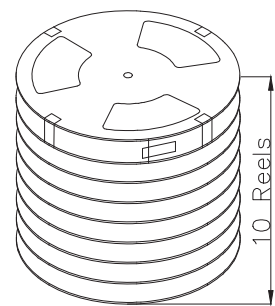
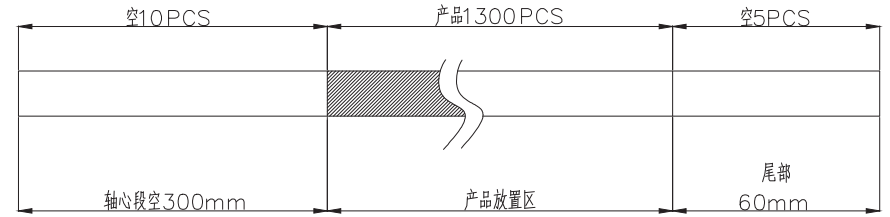
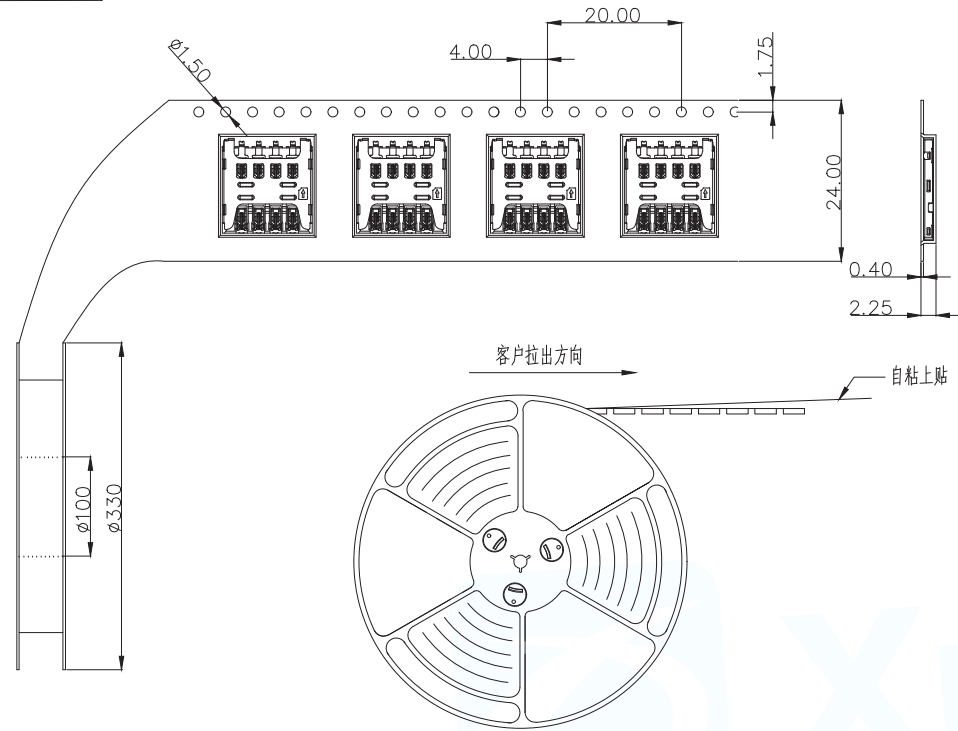


PAD AREA  
 KEEP OUT AREA

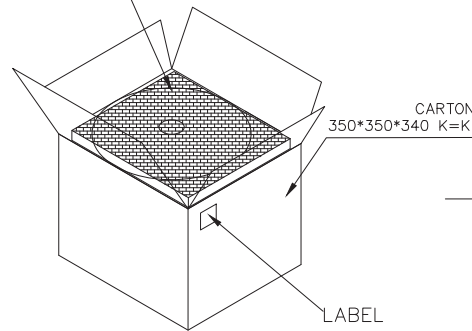
RECOMMENDED PCB LAYOUT  
 GENERAL TOLERANCE  $\pm 0.05$



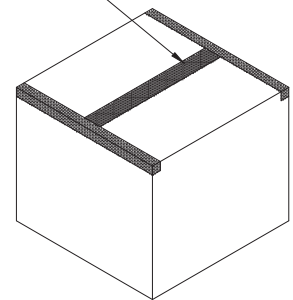
MANUFACTURE DWG		东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co., Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES			TITLE: MICRO SIM CARD PUSH PULL 8PIN H1.5
DECIMALS:	ANGLES:		PAR: SMC-218
X.: $\pm 0.50$	X': $\pm 2^{\circ}$		DWN:
X.X: $\pm 0.30$	X.X': $\pm 1^{\circ}$		CHKD:
X.XX: $\pm 0.20$		APVD:	SCALE: 1:1
CUSTOMER COPY		UNIT: MM	SIZE: A4
		SHEET: 1F1	REV: A



上下各1PCS 珍珠棉



胶纸工字型封箱



MANUFACTURE DWG		 东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES		TITLE: MICRO SIM CARD PUSH PULL 8PIN H1.5 包装图 PAR: SMC-218	
DECIMALS:	ANGLES:	DWN	
X.: ±0.50	X.°: ±2°	CHKD	
X.X: ±0.30	X.X°: ±1°	APVD	
X.XX: ±0.20		SCALE: 1:1	UNIT: MM
		CUSTOMER COPY	SIZE: A4
			SHEET: 1F1
			REV: A